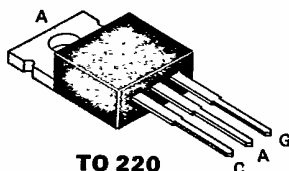


**S1210BH –
S1210NH SCR'S****12 A 200–800 V 10–25 mA**

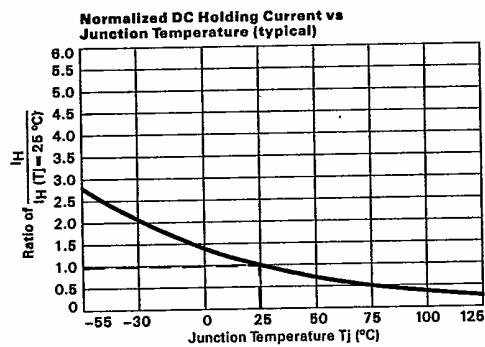
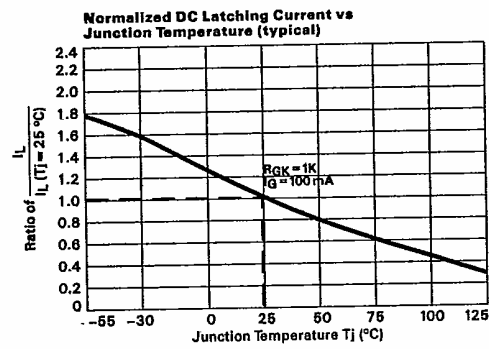
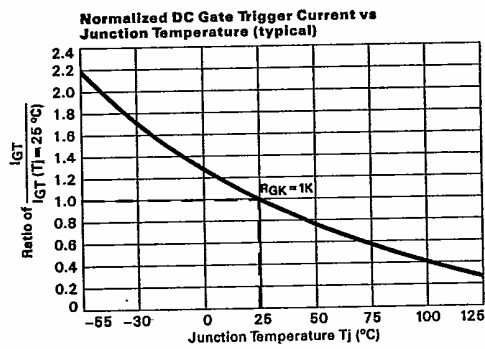
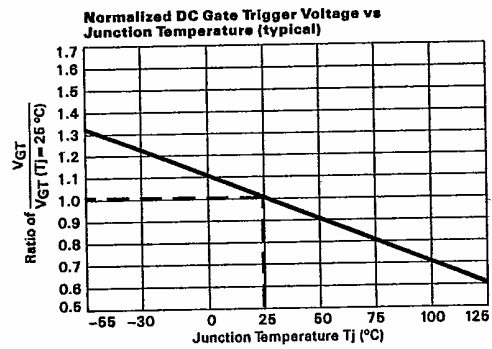
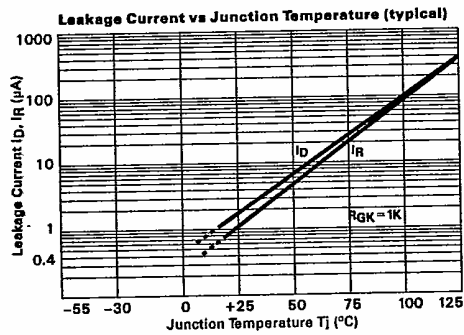
The S1210 series silicon controlled rectifiers are high performance glass passivated PNP devices. These parts are intended for general purpose high current applications where moderate gate insensitivity is required.

**Absolute Maximum Ratings** $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Part Nr.	Symbol	Min.	Max.	Unit	Test Conditions
Repetitive Peak Off State Voltage	S1210BH	V_{DRM} V_{RRM}	200		V	$T_J = -40^\circ\text{C}$ to 125°C $R_{GK} = 1\text{K}\Omega$
	S1210DH		400		V	
	S1210MH		600		V	
	S1210NH		800		V	
On-State Current		$I_T(\text{RMS})$	12		A	All Conduction Angles $T_C = 85^\circ\text{C}$
Average On-State Current		$I_T(\text{AV})$	7.6		A	Half Cycle, $\Theta = 180^\circ$, $T_C = 85^\circ\text{C}$
Nonrept. On-State Current		I_{TSM}	132		A	Half Cycle, 60 Hz
Nonrept. On-State Current		I_{TSM}	120		A	Half Cycle, 50 Hz
Fusing Current		I^2t	72		A^2s	$t = 10\text{ ms}$, Half Cycle
Peak Gate Current		I_{GM}	4		A	$10\mu\text{s}$ max.
Peak Gate Dissipation		P_{GM}	10		W	$10\mu\text{s}$ max.
Gate Dissipation		$P_{G(\text{AV})}$	1		W	20 ms max.
Operating Temperature		T_J	-40	125	$^\circ\text{C}$	
Storage Temperature		T_{stg}	-40	125	$^\circ\text{C}$	
Soldering Temperature		T_{sld}		250	$^\circ\text{C}$	1.6 mm from case, 10 s max.

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Min.	Max.	Unit	Test Conditions
Off-State Leakage Current	I_{DRM}/I_{RRM}		1.5	mA	@ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 125^\circ\text{C}$
Off-State Leakage Current	I_{DRM}/I_{RRM}		5	μA	@ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 25^\circ\text{C}$
On-State Voltage	V_T		1.80	V	at $I_T = 24\text{ A}$, $T_J = 25^\circ\text{C}$
On-State Threshold Voltage	$V_{T(\text{TO})}$		1.0	V	$T_J = 125^\circ\text{C}$
On-State Slope Resistance	r_T		36	$\text{m}\Omega$	$T_J = 125^\circ\text{C}$
Gate Trigger Current	I_{GT}	10	25	mA	$V_D = 7\text{ V}$
Gate Trigger Voltage	V_{GT}		2.0	V	$V_D = 7\text{ V}$
Holding Current	I_H		38	mA	$R_{GK} = 1\text{K}\Omega$
Latching Current	I_L		75	mA	$R_{GK} = 1\text{K}\Omega$
Critical Rate of Voltage Rise	dv/dt	200		$\text{V}/\mu\text{s}$	$V_D = .67 \times V_{DRM}$, $R_{GK} = 1\text{K}\Omega$, $T_J = 125^\circ\text{C}$
Critical Rate of Current Rise	di/dt	100		$\text{A}/\mu\text{s}$	$I_G = 125\text{ mA}$, $di_G/dt = 1.25\text{ A}/\mu\text{s}$, $T_J = 125^\circ\text{C}$
Gate Controlled Delay Time	t_{gd}		500	ns	$I_G = 125\text{ mA}$, $di_G/dt = 1.25\text{ A}/\mu\text{s}$
Commutated Turn-Off Time	t_q		50	μs	$T_C = 85^\circ\text{C}$, $V_D = .67 \times V_{DRM}$, $V_R = 35\text{ V}$, $I_T = I_T(\text{AV})$
Thermal Resistance junc. to case	$R_{\theta jc}$		3	K/W	
Thermal Resistance junc. to amb.	$R_{\theta ja}$		60	K/W	



Typical Characteristics

S12 - Packaged Parts

